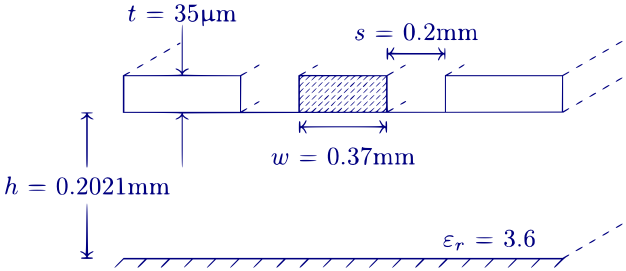
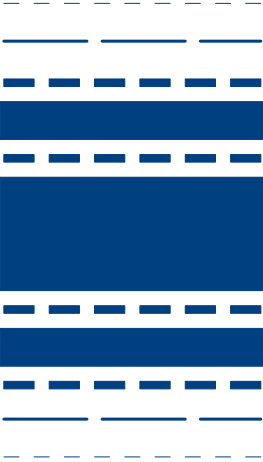
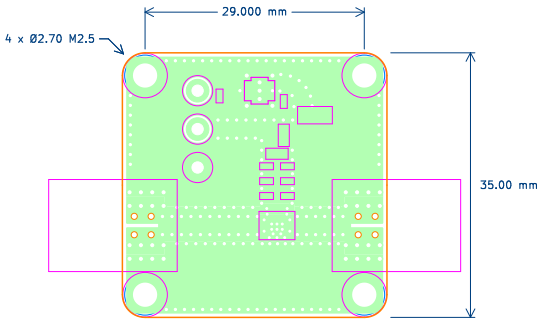


Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	----	----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	----	----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	----	----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	----	----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	----	----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	----	----





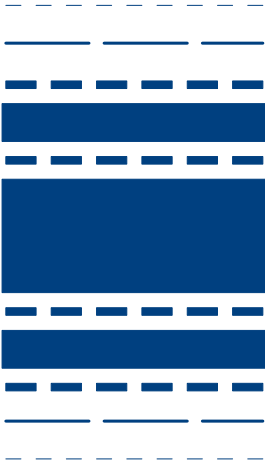
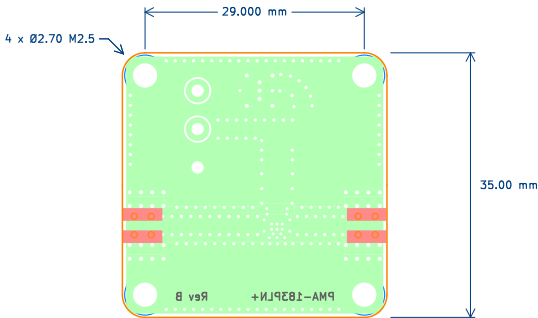
Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	-----	-----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	-----	-----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	-----	-----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	-----	-----

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Sheet:
File: PMA-183PLN+.kicad_pcb
Title: 6000-18000 MHz SMT LNA
Size: USLetter | Date: 7/8/2024
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Rev: B
Id: 1/1

BOT-L4



Layer Material	Layer (File) Name	Thickness (mm)	Permittivity	Loss Tangent
Silkscreen	F.Silk	0.00762	-----	-----
Soldermask	F.Mask	0.0254	4.5	0.029
Copper	F.Cu	0.0432	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	In1.Cu	0.0175	-----	-----
FR408-HR	-----	0.9906	3.64	0.0098
Copper	In2.Cu	0.0175	-----	-----
FR408HR 2113	-----	0.2021	3.6	0.010
Copper	B.Cu	0.0432	-----	-----
Soldermask	B.Mask	0.0254	4.5	0.029
Silkscreen	B.Silk	0.00762	-----	-----

Remy Nguyen

Sheet:
File: PMA-183PLN+.kicad_pcb
Title: 6000-18000 MHz SMT LNA
Size: USLetter | Date: 7/8/2024
KiCad E.D.A. kicad 7.0.5

Rev: B
Id: 1/1